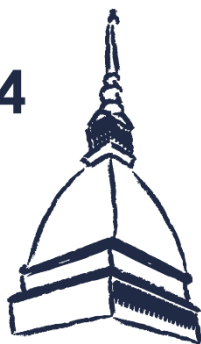




The 14th International Workshop on the Electromagnetic Compatibility of Integrated Circuits

EMC COMPO 2024

October 7th-9th, 2024
Politecnico di Torino
Torino, Italy



CALL FOR PAPER

ORGANIZATION AND VENUE

Welcome back to the land of Technology and Culture! After a successful EMC COMPO 2007, the EMC Community will gather again in Torino, Italy, from October 7th to 9th, 2024, to exchange views on research progress and technological developments in the various topics described hereunder.

The 14th International Workshop on the Electromagnetic Compatibility of Integrated Circuits, EMC COMPO 24 is co-sponsored by the IEEE EMC Society (EMCS).

The conference will take place at the Technical University of Torino, in Torino, Italy. (More info at <http://www.polito.it>)

AIMS OF THE WORKSHOP

EMC COMPO is a unique event attracting experts on the electromagnetic compatibility of integrated circuits and modules from all over the world.

Aiming at exchanging experience among fellow professionals and academics, and bearing in mind the role of electronic components in terms of electromagnetic compatibility, safety and reliability of electronic modules and systems, EMC COMPO 2024 is the right place to achieve this goal. EMC COMPO in Torino will provide the opportunity to discuss hot topics through oral, poster sessions and tutorials.

PAPER SUBMISSION

Authors are invited to submit original contributions in two-column and either one-page format for abstract submission (in proceedings only, Oral/Poster) or full-length (2–4 pages) format for paper submission (for IEEE Xplore Publication, Oral/Poster) through the online Paper Submission System at the workshop website. The paper must follow the two-column A4 format of an IEEE Manuscript Template for Conference Proceedings.

save the dates!

**Full paper
submission
deadline**

April 13th, 2024

**Acceptance
notification**

June 8th, 2024

**Final paper
Submission**

July 15th, 2024

TOPICS

- Susceptibility to EMI of analog and mixed signal IPs
- EMC of analog and digital sensors
- EMC of ICs for biomedical applications
- EMC of ICs for wireline communications
- Power electronics EMC/EMI
- Electromagnetic emission of core blocks and I/Os
- EMC issues in System-on-chip (SoC), System-in-Package (SiP), and 3D ICs
- Substrate coupling in smart power ICs
- EMC-aware Design of ICs and Guidelines
- Tools to handle EMC at IC and module level
- SI and PI at IC and PCB level
- Measurement methods for chip level EMC analysis
- EMC Standards and regulations
- Materials for improved EMC of ICs
- Long term electromagnetic robustness of ICs
- Influence of IC EMC on system design





TUTORIALS AND SHORT COURSES

Tutorials and short courses will be organized as interactive educational presentations to provide up-to-date practical help to those new to the subject or requiring an update, as well as to address in-depth topical subjects. Tutorials and short courses are planned for the first day of the workshop, i.e., October 7th, 2024. For accepted proposals, the tutorial organizer will be responsible for soliciting presentations, corresponding with session speakers, corresponding with the Workshop Local Committee, and moderating the session at the workshop. Please, send the tutorial and short course proposals to tpc.emccompo24@polito.it before June 6th, 2024.

SPONSORSHIP

It is also possible to take advantage of many sponsorship opportunities. Proposals of Diamond Sponsor, Gold Sponsor and Silver Sponsor packages are available, but any form of sponsoring (technical, financial or any other) to promote the workshop is very welcome. To become a conference sponsor please write to info.emccompo24@polito.it.

EXHIBITION

The Workshop will be accompanied by a technical exhibition on IC EMC and RF/microwave measurements and instrumentation. We also invite manufacturers and dealers of EMC-related equipment and tools, measurement and test equipment, spectrum monitoring and measurement systems, protecting device and components, microwave instrumentation, electromagnetic analysis and synthesis software.

The technical exhibition will be held from October 7th, 2024, to October 9th, 2024. The exhibition area is directly accessible from the conference rooms and ensure that delegates have the opportunity to visit it. An exhibition booth can be ordered. To exhibit, send the application before **July 30th, 2024** to exhibits.emccompo24@polito.it. For more details please visit the conference website at the page www.emccompo2024.it/for-exhibitors/.

INFO FOR AUTHORS AND EXHIBITORS

Paper submission starting	Feb. 1 st , 2024
Deadline for paper submission	April 13 th , 2024
Tutorial Proposal deadline	June 6 th , 2024
Notification of acceptance	June 8 th , 2024
Final paper submission	July 15 th , 2024

LOCAL ORGANIZING COMMITTEE

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Franco Fiori Politecnico di Torino

TPC Chair

Flavia Grassi Politecnico di Milano

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For exhibitors exhibits.emccompo24@polito.it

